

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. – 14. (Cancelled)

15. (Currently Amended) A method of manufacturing a circuit board comprising:

~~the~~ a step of mounting a first component on a substrate by a solder connection;

~~the~~ a step of arranging an anisotropic conductive film within a band region of a surface on a predetermined position of the substrate;

~~the~~ a step of arranging a second component on the anisotropic conductive film;
and

~~the~~ a step of thermocompression-bonding the second component to said substrate with said anisotropic conductive film held therebetween;

wherein said step of arranging said anisotropic conductive film ~~on the predetermined position~~ within said band region of said substrate is performed after said step of mounting the first component on said substrate by the solder connection;

said step of thermocompression-bonding is performed with a compression bonding head; and

the band region is wider than the head.

16. (Previously Presented) A method of manufacturing a circuit board according to claim 15, wherein said step of mounting said first component on said substrate by the solder connection includes a reflow treatment.

17. – 20. (cancelled)

21. (Currently Amended) A method of manufacturing a circuit board in which components are mounted thereto, comprising:

a.) selecting a band region on a surface of the circuit board;
b.) soldering a first component onto the circuit board outside of the band region; and

c.) after step b.), mounting a second component on the substrate within the band region with an anisotropic conductive film,

wherein step c.) includes a step of thermocompression-bonding the second component to said substrate with a compression bonding head; and the band region is wider than the head.

22. (Previously Presented) The method of claim 21 where step c.) is performed with a heated compression bonding head, and

wherein the band region is selected to correspond generally to the areas over which the head travels during step c.) thereby preventing impact of the head with the first component and isolating the first component from the heat generated by the head.

23. (Previously Presented) The method of claim 15, wherein the first component is selected from the group of passive and mechanical components, and the second component comprises a semiconductor device.

24. (Cancelled)

25. (Currently Amended) The method of claim 24 15, wherein alignment marks are provided outside the band region.

26. (Currently Amended) The method of claim 24 15, wherein the bonding region is selected by performing a solder reflow process.

27. (Currently Amended) The method of claim 24 15, wherein the band region divides a first set of first components on one part of the substrate and a second set of first components on a second part of the substrate.

28. (Previously Presented) The method of claim 23, wherein the second component is selected from the group of a power source IC and a power source LSI.

29. (Currently Amended) The method of claim 24 15, wherein the band region extends from one end of the substrate to another end of the substrate.

30. (Currently Amended) The method of claim 24 15, wherein the band region extends rectilinearly along the substrate.

31. (Currently Amended) The method of claim 24 15, further comprising:
forming wiring patterns on the substrate in the band region.

32. (Previously Presented) The method of claim 15, further comprising:
forming a dummy electrode at a position associated with the second component.

33. (New) A method of manufacturing a circuit board comprising:
a step of mounting first components on a substrate by a solder connection within first regions and a second region;

a step of arranging an anisotropic conductive film on a predetermined position of the substrate;

a step of arranging a second component on the anisotropic conductive film within a band region other than the first regions and the second region; and

a step of thermocompression-bonding the second component to the substrate with the anisotropic conductive film held therebetween in a bonding region within the band region;

wherein the step of arranging the anisotropic conductive film on the predetermined position of the substrate is performed after the step of mounting the first component on the substrate by the solder connection;

the band region extends from the bonding region toward output side terminals of the substrate;

the first regions are located on both sides of the bonding region; and

the second region is located between the output side terminals and the first region.

34. (New) A method of manufacturing a circuit board in which components are mounted thereto, comprising:

a) selecting a band region on a surface of the circuit board;

b) soldering first components onto the circuit board within first regions and a second region outside of the band region; and

c) after step b) mounting a second component on the substrate within the band region with an anisotropic conductive film in a mounting region within the band region,

wherein the band region extends from the mounting region toward output side terminals of the substrate;

the first regions are located on both sides of the mounting region, and

the second region is located between the output side terminals and the first region.